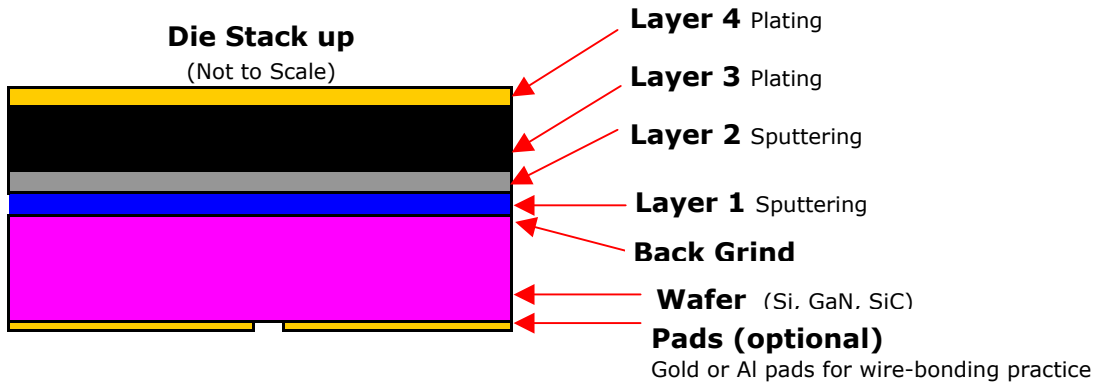




Customer Questionnaire IGBT Back Metal Wafer with Plating Layers

www.topline.tv/igbt_wafer.html



| | | | | |
|-----|--------------------------|-----------------------|--------------------------------|--------------------------------|
| 1) | Wafer Material: | [] Si Silicon | [] GaN Gallium Nitride | [] SiC Silicon Carbide |
| 2) | Die Size: | _____mm | x | _____mm |
| 3) | Die Thickness: | _____um | | |
| 4) | Back Grind Mesh: | [] #600 | [] Other | _____ |
| 5) | Layer 1 Material: | [] Ti | [] Other | _____ |
| 6) | Layer 1 Thick: | [] 1000A | [] Other | _____ |
| 7) | Layer 2 Material: | [] Ni | [] Other | _____ |
| 8) | Layer 2 Thick: | [] 1000A | [] Other | _____ |
| 9) | Layer 3 Material: | [] Ni | [] Other | _____ |
| 10) | Layer 3 Thick: | [] 2.0 ~ 4.0um | [] Other | _____ |
| 11) | Layer 4 Material: | [] Au | [] Sn | [] Other _____ |
| 12) | Layer 4 Thick: | [] 2.0 ~ 4.0um | [] Other | _____ |
| 13) | Wire Bond Pad: | [] None | [] Daisy Chain | Pad Size: _____ |
| 14) | Packaging: | [] Waffle Pack | [] Tape and Ring | [] Other _____ |
| 15) | Quantity Die: | Min _____pcs | ~ | Max _____pcs |

Company: _____

Your Name: _____

Title _____

email: _____

Tele: _____

Date: _____